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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of Conveying Party(ies):

(1) KENJI HANADA, (2) MASAKI NAKANISHI,
(3) TOMOO MATSUZAWA, (4) KOJI SHIDA, (5)
KAZUTOSHI TAKASHIMA

Additional names of conveying parties attached: ☐ Yes ☒ No

3. Nature of Conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other:

Execution Date: (1) (2) October 10, 2003 (3)(4)(5)
October 15, 2003

2. Name and Address of Receiving Party(ies):

Name: **Renesas Technology Corporation**
Address: 4-1, Marunouchi 2-chome
City: Chiyoda-ku, Tokyo
Japan

And

Name: **Renesas Eastern Japan Semiconductor, Inc.**
Address: 3-2, Fujihashi 3-chome
City: Ome-shi, Tokyo
Japan

4. (a) Patent Application Number(s):

10/651,087

If this document is being filed together with a new application,
the execution date of the application is:

☐ Additional Numbers Attached.

4. (b) Patent Numbers:

5. Name and Address of Party to whom Correspondence
Concerning this Document Should be Mailed:

Name: **Stanley P. Fisher**

Address: **Reed Smith LLP**
3110 Fairview Park Dr.
Suite 1400
Falls Church, VA. 22042

6. Total Number of Applications and Patents Involved: 1

7. Total Fee: **\$40.00**
(37 C.F.R. § 3.41)

- ☒ Enclosed.
☒ Authorized to be charged to deposit account.

8. Deposit Account Number: **08-1480**

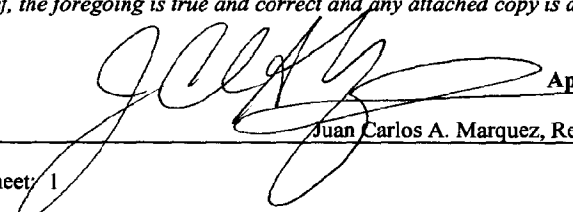
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9. Statement and Signature:

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the
original document.

Stanley P. Fisher, Registration No. 24, 344

 April 27, 2004
Juan Carlos A. Marquez, Registration No. 34,072

Total number of pages comprising cover sheet: 1

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ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp., and Renesas Eastern Japan Semiconductor, Inc., corporations organized under the laws of Japan, located at 4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo, Japan, and 3-2, Fujihashi 3-chome, Ome-shi, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., and Renesas Eastern Japan Semiconductor, Inc., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

MANUFACTURING METHOD OF SOLID-STATE IMAGE SENSING DEVICE

Serial No. 10/651,087 filed on 29/August/2003
invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Technology Corp., and Renesas Eastern Japan Semiconductor, Inc., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp., and Renesas Eastern Japan Semiconductor, Inc.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) <u>Kenji HANADA</u> Kenji HANADA	<u>10 / October / 2003</u>
2) <u>Masaki NAKANISHI</u> Masaki NAKANISHI	<u>10 / October / 2003</u>
3) <u>Koji SHIDA Tomoo MATSUZAWA</u> K.S. Tomoo MATSUZAWA	<u>15 / October / 2003</u>
4) <u>Koji SHIDA</u> Koji SHIDA	<u>15 / October / 2003</u>
5) <u>Kazutoshi TAKASHIMA</u> Kazutoshi TAKASHIMA	<u>15 / October / 2003</u>
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____